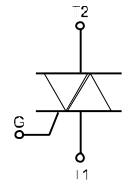
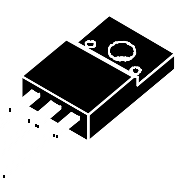



Description	16A TRIACs												
<div style="display: flex; flex-direction: column; align-items: center;">   <p><b>ITO- 220AB</b></p> </div> <p><b>MAIN FEATURES</b></p> <table border="1"> <thead> <tr> <th>Symbol</th> <th>Value</th> <th>Unit</th> </tr> </thead> <tbody> <tr> <td><math>I_{T(RMS)}</math></td> <td>4</td> <td>A</td> </tr> <tr> <td><math>V_{DRM}/V_{RRM}</math></td> <td>600 &amp; 800</td> <td>V</td> </tr> <tr> <td><math>I_{GT(QI)}</math></td> <td>10 to 50</td> <td>mA</td> </tr> </tbody> </table>	Symbol	Value	Unit	$I_{T(RMS)}$	4	A	$V_{DRM}/V_{RRM}$	600 & 800	V	$I_{GT(QI)}$	10 to 50	mA	<div style="display: flex; justify-content: space-between;"> <div> <p>Passivated, new generation, high Commutation triacs in a ITO-220AB isolated full pack plastic package</p> <ul style="list-style-type: none"> <li>● Very high commutation performance Maximized at each gate sensitivity</li> <li>● High isolation voltage</li> <li>● High immunity to dV/dt</li> <li>● Wide range of gate sensitivities</li> </ul> </div>  </div> <p><math>I_{GT} \leq 50\text{mA}</math> (BTA316X series B)  <math>I_{GT} \leq 35\text{mA}</math> (BTA316X series C)  <math>I_{GT} \leq 10\text{mA}</math> (BTA316X series E)</p>
Symbol	Value	Unit											
$I_{T(RMS)}$	4	A											
$V_{DRM}/V_{RRM}$	600 & 800	V											
$I_{GT(QI)}$	10 to 50	mA											

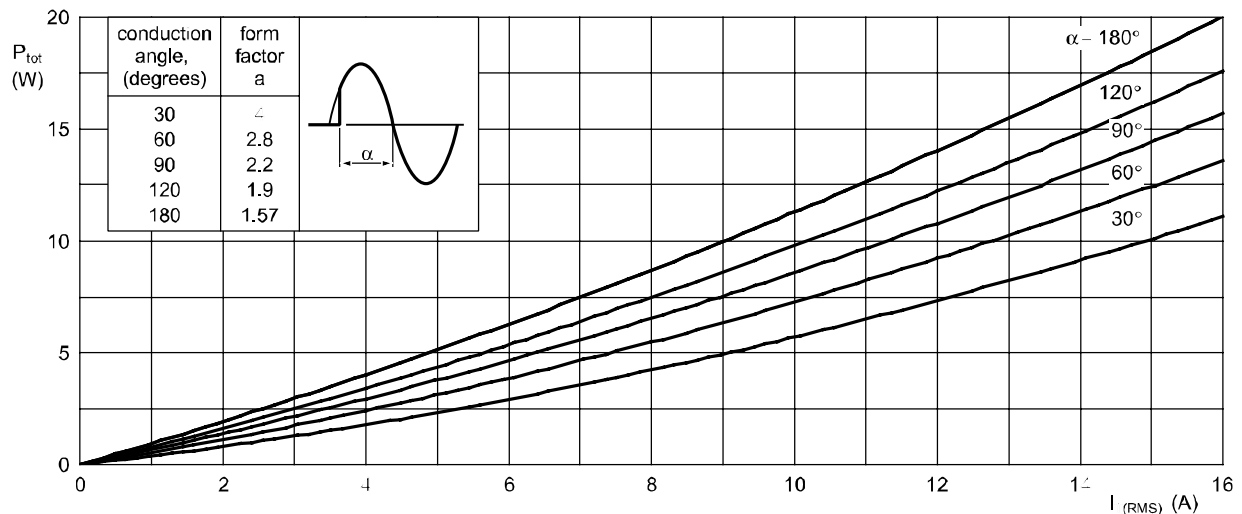
Absolute Maximum Rating				
Symbol	Parameter	Conditions	Value	Unit
$V_{DRM}$	repetitive peak off-state voltage	BTA316X-600	600	V
		BTA316X-800	800	
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_j(\text{init}) = 25\text{ }^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; (see Fig.2, Fig.3)	140	A
		full sine wave; $T_j(\text{init}) = 25\text{ }^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$ ; (see Fig.2, Fig.3)	150	
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 45\text{ }^\circ\text{C}$ (see Fig.4, Fig.5)	16	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; sine-wave pulse	98	$\text{A}^2\text{s}$
$di/dt$	rate of rise of on-state current	$I_{TM} = 20\text{ A}$ ; $I_G = 0.2\text{ A}$ ; $di/dt = 0.2\text{ A}/\mu\text{s}$	100	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current		2	A
$P_{GM}$	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
$T_{stg}$	storage temperature		-40~+150	$^\circ\text{C}$
$T_j$	junction temperature		125	$^\circ\text{C}$

Static Characteristics (T <sub>j</sub> = 25°C, unless otherwise specified)						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I <sub>GT</sub>	Gate trigger current <b>BTA316X-600B</b> <b>BTA316X-800B</b>	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+;(see Fig.8)	2	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-;(see Fig.8)	2	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-;(see Fig.8)	2	-	50	mA
	Gate trigger current <b>BTA316X-600C</b> <b>BTA316X-800C</b>	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+;(see Fig.8)	2	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-;(see Fig.8)	2	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-;(see Fig.8)	2	-	35	mA
	Gate trigger current <b>BTA316X-600E</b> <b>BTA316X-800E</b>	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+;(see Fig.8)	-	-	10	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-;(see Fig.8)	-	-	10	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-;(see Fig.8)	-	-	10	mA
I <sub>L</sub>	latching current <b>BTA316X-600B</b> <b>BTA316X-800B</b>	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G+;(see Fig.10)	-	-	60	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G-;(see Fig.10)	-	-	90	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2- G-;(see Fig.10)	-	-	60	mA
	latching current <b>BTA316X-600C</b> <b>BTA316X-800C</b>	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G+;(see Fig.10)	-	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G-;(see Fig.10)	-	-	60	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2- G-;(see Fig.10)	-	-	50	mA
	latching current <b>BTA316X-600E</b> <b>BTA316X-800E</b>	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G+;(see Fig.10)	-	-	25	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2+ G-;(see Fig.10)	-	-	30	mA
		V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; T2- G-;(see Fig.10)	-	-	30	mA
I <sub>H</sub>	holding current <b>BTA316X-600B</b> <b>BTA316X-800B</b>	V <sub>D</sub> = 12 V; I <sub>GT</sub> = 0.1 A; (see Fig.11)	-	-	60	mA
	holding current <b>BTA316X-600C</b> <b>BTA316X-800C</b>		-	-	35	mA
	holding current <b>BTA316X-600E</b> <b>BTA316X-800E</b>		-	-	15	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 18 A; (see Fig.9)	-	1.3	1.5	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; (See Fig.7)	-	0.8	1.5	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C (See Fig.7)	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125 °C	-	0.1	0.5	mA

Dynamic Characteristics (T <sub>j</sub> = 25°C, unless otherwise specified)						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
dV <sub>D</sub> /dt	rate of rise of off-state voltage <b>BTA316X-600B</b> <b>BTA316X-800B</b> <b>BTA316X-600C</b> <b>BTA316X-800C</b> <b>BTA316X-600E</b> <b>BTA316X-800E</b>	V <sub>DM</sub> =0.67 x V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125 °C Exponential waveform; gate open circuit	1000	-	-	V/μs
			500	-	-	V/μs
			60	-	-	V/μs
t <sub>gt</sub>	gate-controlled turn-on time	I <sub>TM</sub> = 20 A; V <sub>D</sub> = V <sub>DRM(max)</sub> ; I <sub>G</sub> = 0.1 A; dI <sub>G</sub> /dt = 5 A/μs	-	2	-	μs

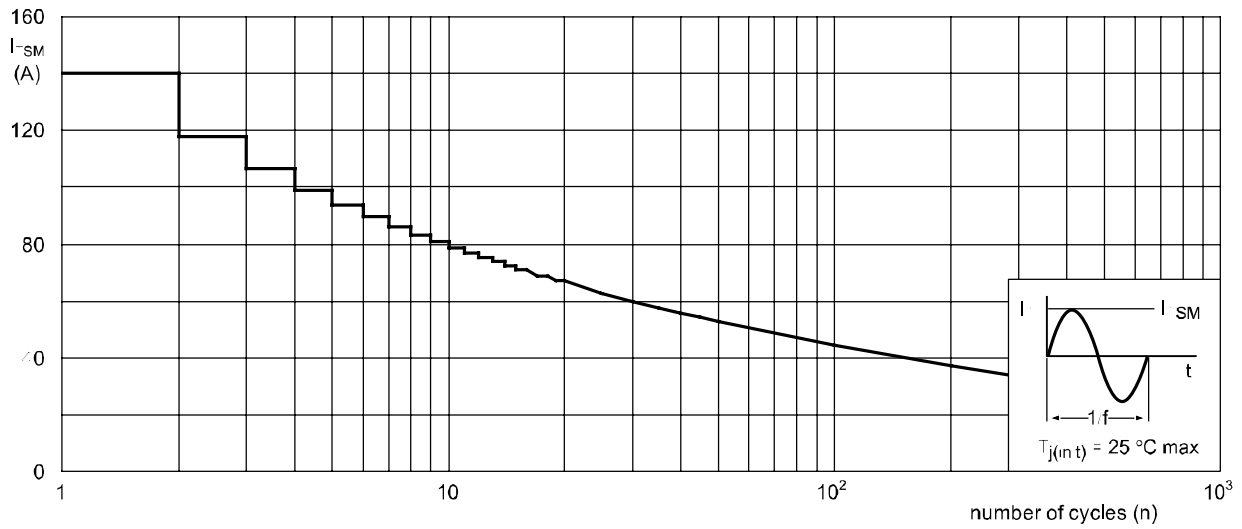
Dynamic Characteristics (T <sub>j</sub> = 25°C, unless otherwise specified)						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
di <sub>com</sub> /dt	rate of change of commutating current BTA316X-600B BTA316X-800B	V <sub>DM</sub> = 400 V; T <sub>j</sub> = 125 °C; I <sub>T(RMS)</sub> = 16 A; without snubber ; gate open circuit	20	-	-	A/ms
	BTA316X-600C BTA316X-800C		15	-	-	A/ms
	BTA316X-600E BTA316X-800E		5	-	-	A/ms
	BTA316X-600B BTA316X-800B	V <sub>DM</sub> = 400 V; T <sub>j</sub> = 125 °C; I <sub>T(RMS)</sub> = 16 A; dV/dt = 10 V/μs; gate open circuit	-	-	-	A/ms
	BTA316X-600C BTA316X-800C		-	-	-	A/ms
	BTA316X-600E BTA316X-800E		-	-	8	A/ms
	BTA316X-600B BTA316X-800B	V <sub>DM</sub> = 400 V; T <sub>j</sub> = 125 °C; I <sub>T(RMS)</sub> = 16 A; dV/dt = 1 V/μs; gate open circuit	-	-	-	A/ms
	BTA316X-600C BTA316X-800C		-	-	-	A/ms
	BTA316X-600E BTA316X-800E		-	-	12	A/ms

Thermal Resistances						
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>th(j-L)</sub>	thermal resistance from junction to mounting base	full or half cycle without heatsink compound (see Fig.6)			5.5	K/W
		full or half cycle with heatsink compound (see Fig.6)			4.0	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		55		K/W



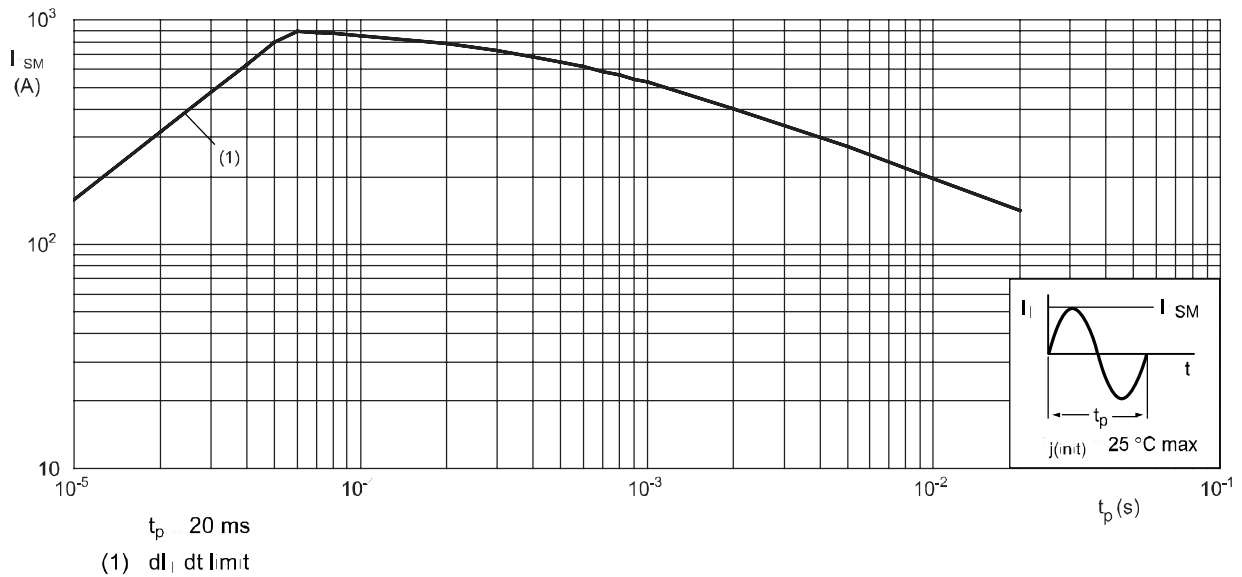
$\alpha$  = conduction angle

**Fig 1. Total power dissipation as a function of RMS on-state current; maximum values**

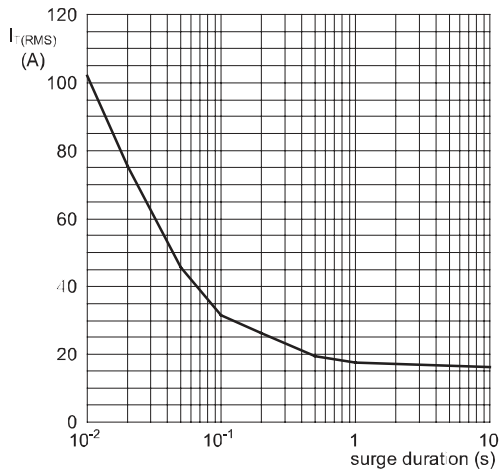


f = 50 Hz

**Fig 2. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values**

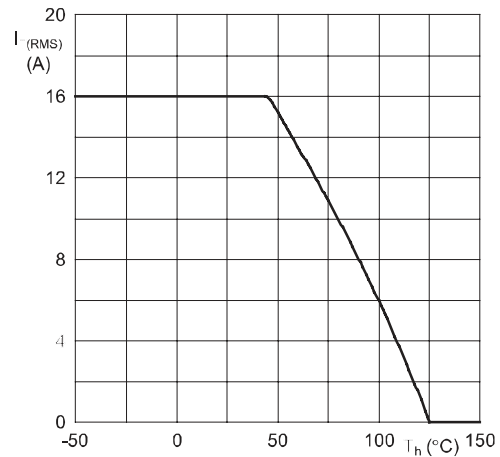


**Fig 3. Non-repetitive peak on-state current as a function of pulse duration; maximum values**

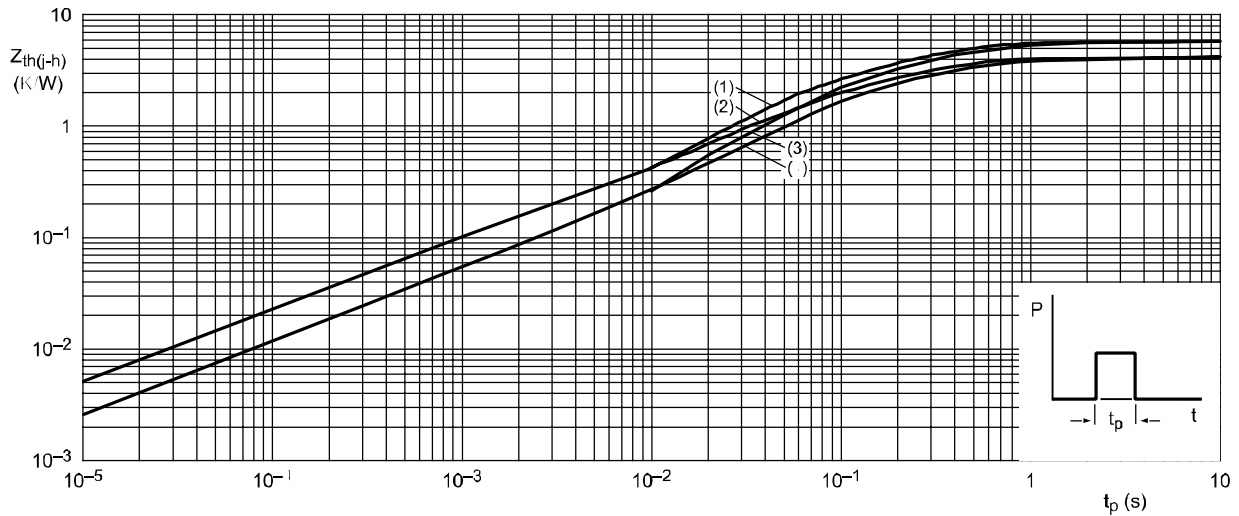


f = 50 Hz;  
T<sub>h</sub> = 45 °C

**Fig 4. RMS on-state current as a function of surge duration; maximum values**

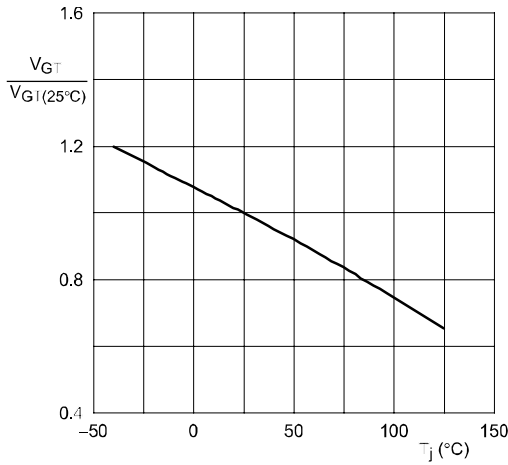


**Fig 5. RMS on-state current as a function of heatsink temperature; maximum values**

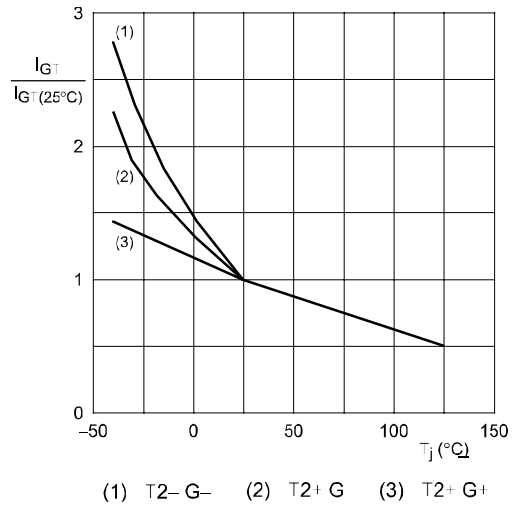


- (1) Unidirectional (half cycle) without heatsink compound
- (2) Unidirectional (half cycle) with heatsink compound
- (3) Bidirectional (full cycle) without heatsink compound
- (4) Bidirectional (full cycle) with heatsink compound

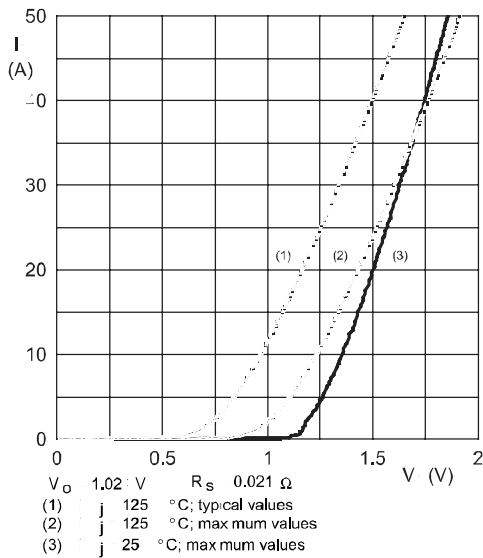
**Fig 6. Transient thermal impedance from junction to heatsink as a function of pulse duration**



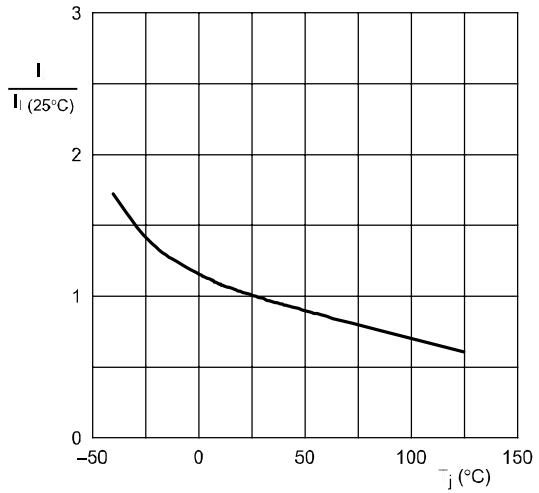
**Fig 7. Normalized gate trigger voltage as a function of junction temperature**



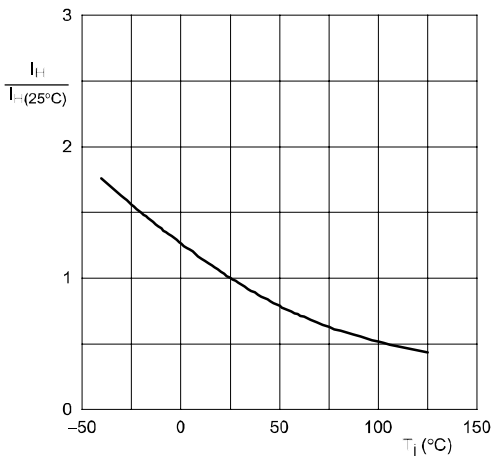
**Fig 8. Normalized gate trigger current as a function of junction temperature**



**Fig 9. On-state current as a function of on-state voltage**



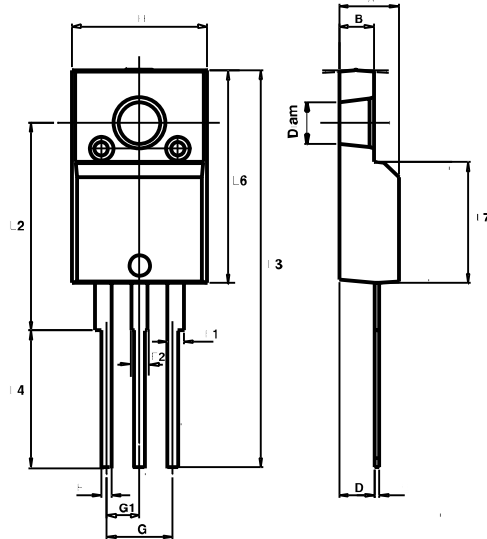
**Fig 10. Normalized latching current as a function of junction temperature**



**Fig 11. Normalized holding current as a function of junction temperature**

**PACKAGE MECHANICAL DATA**

ITO-220AB (Plastic)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.50	2.70	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.40	0.70	0.016	0.028
F	0.75	1.00	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.10	2.70	0.094	0.106
H	10.00	10.40	0.394	0.409
L2	16.00 typ.		0.630 typ.	
L3	28.60	30.60	1.125	1.205
L4	9.80	10.60	0.386	0.417
L6	15.90	16.40	0.626	0.646
L7	9.00	9.30	0.354	0.366
Diam	3.00	3.20	0.118	0.126

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